

4-PIN SOP, 1.1 Ω LOW ON-STATE RESISTANCE 1-ch Optical Coupled MOS FET

DESCRIPTION

The PS7200K-1A is a low output capacitance solid state relay containing a GaAs LED on the light emitting side (input side) and MOS FETs on the output side.

It is suitable for high-frequency signal control, due to its low $C \times R$, low on-state resistance, and low off-state leakage current.

FEATURES

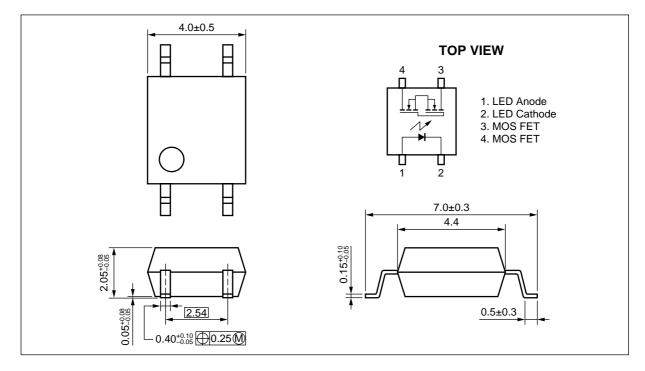
- Low $C \times R$ ($C \times R = 10.5 \text{ pF} \bullet \Omega$)
- Low on-state resistance ($R_{on} = 1.1 \Omega TYP$.)
- Low off-state leakage current (ILoff = 0.03 nA TYP.)
- High-speed turn-on time (ton = 0.1 ms TYP.)
- 1 channel type (1 a output)
- Designed for AC/DC switching line changer
- Small and thin package (4-pin SOP, Height = 2.1 mm)
- High isolation voltage (BV = 1 500 Vr.m.s.)
- Low offset voltage
- Ordering number of taping product: PS7200K-1A-E3, E4, F3, F4

APPLICATIONS

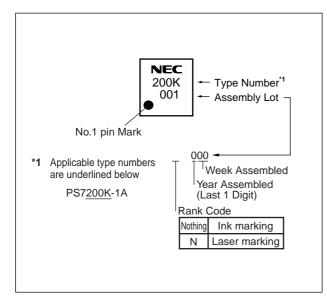
Measurement equipment

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PACKAGE DIMENSIONS (UNIT: mm)



MARKING EXAMPLE



Part Number	Package	Packing Style	Application Part Number ^{*1}
PS7200K-1A	4-pin SOP	Magazine case 100 pcs	PS7200K-1A
PS7200K-1A-E3		Embossed Tape 900 pcs/reel	
PS7200K-1A-E4			
PS7200K-1A-F3		Embossed Tape 3 500 pcs/reel	
PS7200K-1A-F4			

ORDERING INFORMATION (Solder Contains Lead)

*1 For the application of the Safety Standard, following part number should be used.

ORDERING INFORMATION (Pb-Free)

Part Number	Package	Packing Style	Application Part Number ^{*1}
PS7200K-1A-A	4-pin SOP	Magazine case 100 pcs	PS7200K-1A
PS7200K-1A-E3-A		Embossed Tape 900 pcs/reel	
PS7200K-1A-E4-A			
PS7200K-1A-F3-A		Embossed Tape 3 500 pcs/reel	
PS7200K-1A-F4-A			

*1 For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (TA = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current (DC)	lf	50	mA
	Reverse Voltage	Vr	5.0	V
	Power Dissipation	Po	50	mW
	Peak Forward Current *1	IFP	1	А
MOS FET	Break Down Voltage	VL	40	V
	Continuous Load Current	lı.	200	mA
	Pulse Load Current ^{*2} (AC/DC Connection)	Ilp	400	mA
	Power Dissipation	PD	100	mW
Isolation Voltage *3		BV	1 500	Vr.m.s.
Total Power Dissipation		Ρτ	150	mW
Operating Ambient Temperature		TA	–40 to +85	°C
Storage Temperature		Tstg	-40 to +100	°C

*1 PW = 100 µs, Duty Cycle = 1%

*2 PW = 100 ms, 1 shot

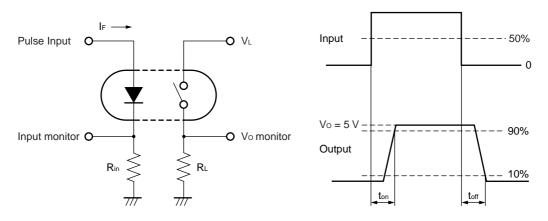
*3 AC voltage for 1 minute at $T_A = 25^{\circ}C$, RH = 60% between input and output

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	lF	2	10	20	mA
LED Off Voltage	VF	0		0.5	V

ELECTRICAL CHARACTERISTICS (TA = 25°C)

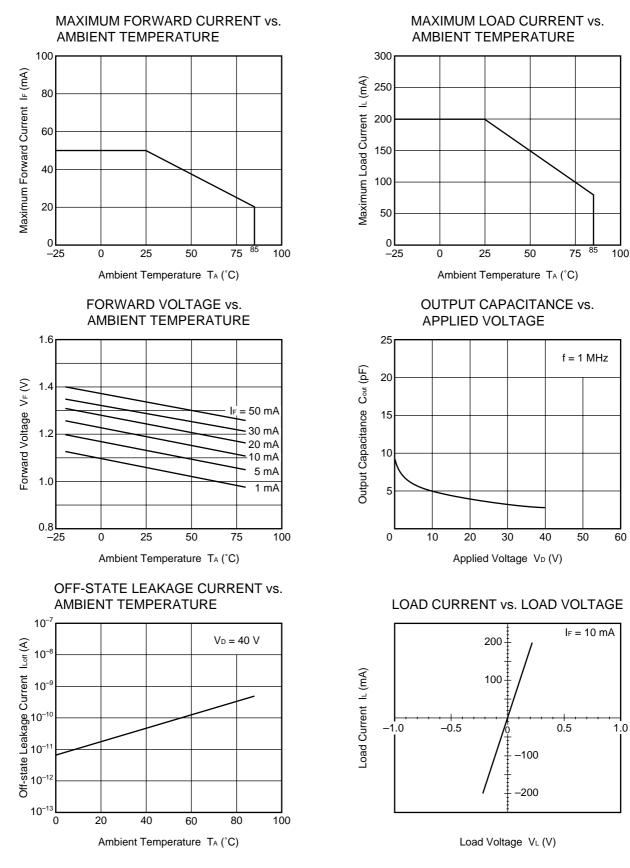
	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	IF = 10 mA		1.2	1.4	V
	Reverse Current	Ir	V _R = 5 V			5.0	μA
MOS FET	Off-state Leakage Current	Loff	V _D = 40 V		0.03	10	nA
	Output Capacitance	Cout	V _D = 0 V, f = 1 MHz		9.6		pF
Coupled	LED On-state Current	Fon	I∟ = 200 mA			2.0	mA
	On-state Resistance	Ron1	IF = 10 mA, IL = 100 mA		1.1	2.0	Ω
		Ron2	I_{F} = 10 mA, I_{L} = 200 mA, $t \leq$ 10 ms		1.4	2.0	
	Turn-on Time ^{*1, 2}	ton	IF = 10 mA, Vo = 5 V, RL = 500 Ω,		0.1	0.5	ms
	Turn-off Time ^{*1, 2}	toff	PW ≥ 10 ms		0.1	1.0	
	Isolation Resistance	R ⊦o	VI-O = 1.0 kVDC	10 ⁹			Ω
	Isolation Capacitance	CI-O	V = 0 V, f = 1 MHz		0.3		pF

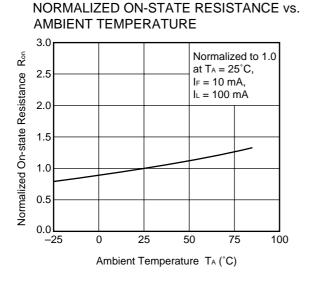
*1 Test Circuit for Switching Time



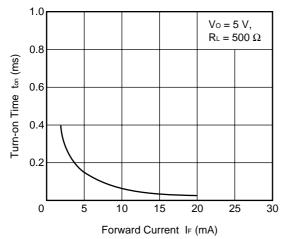
*2 The turn-on time and turn-off time are specified as input-pulse width ≥ 10 ms.
 Be aware that when the device operates with an input-pulse width of under 10 ms, the turn-on time and turn-off time will increase.

TYPICAL CHARACTERISTICS (TA = 25°C, unless otherwise specified)

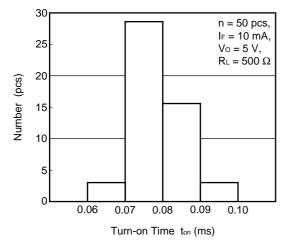




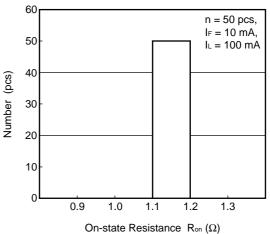
TURN-ON TIME vs. FORWARD CURRENT



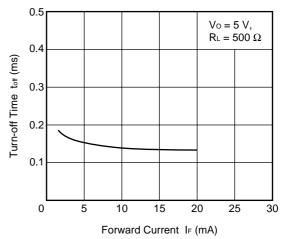
TURN-ON TIME DISTRIBUTION



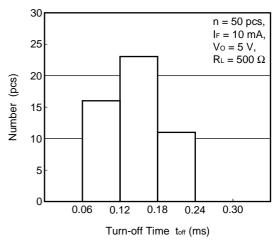


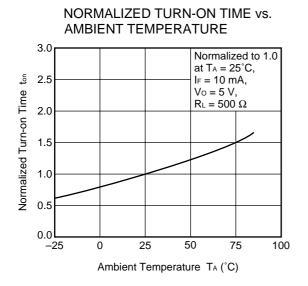


TURN-OFF TIME vs. FORWARD CURRENT

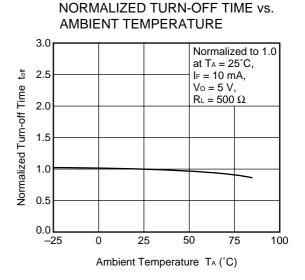


TURN-OFF TIME DISTRIBUTION

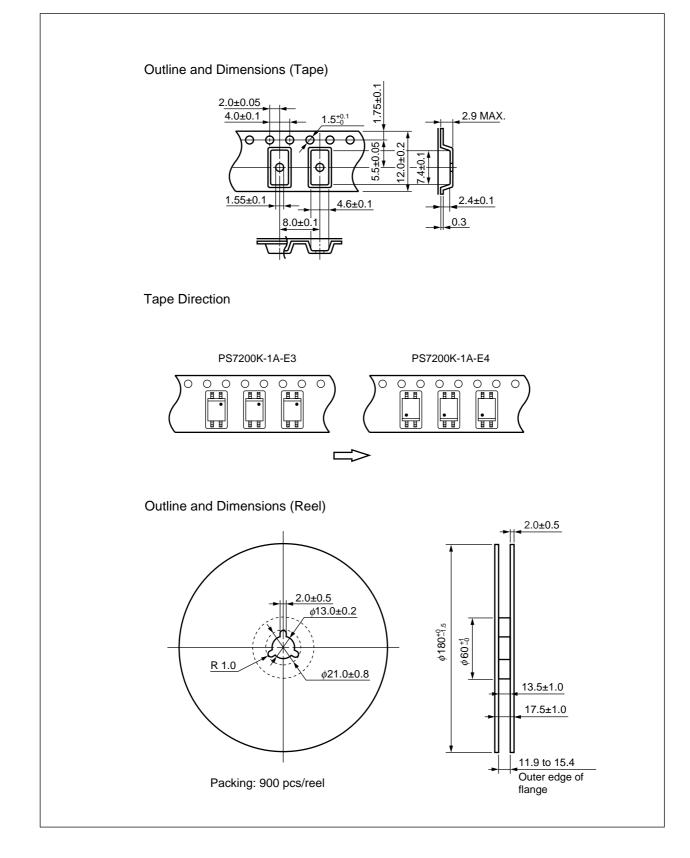


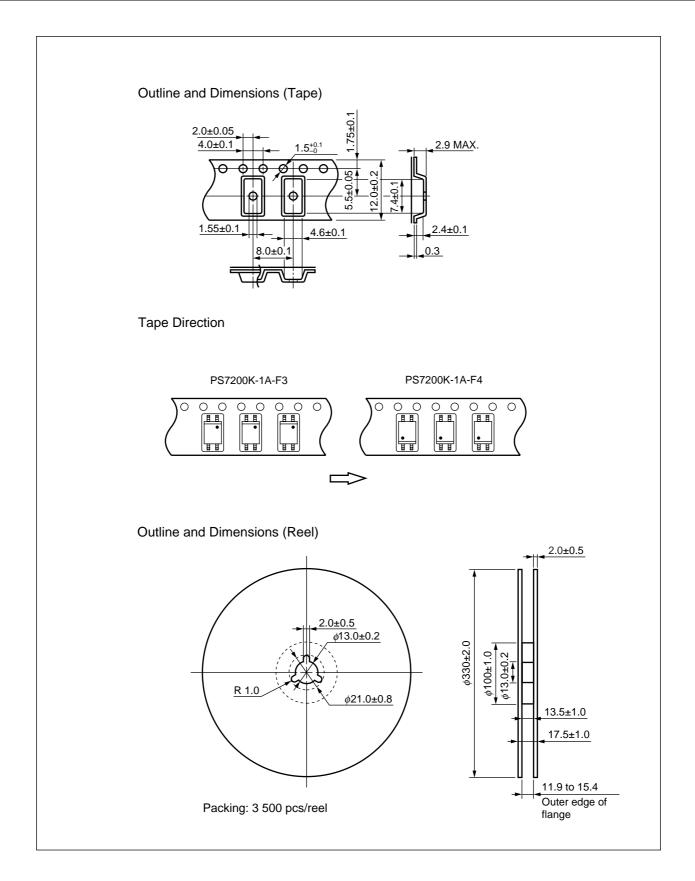


Remark The graphs indicate nominal characteristics.



★ TAPING SPECIFICATIONS (UNIT: mm)





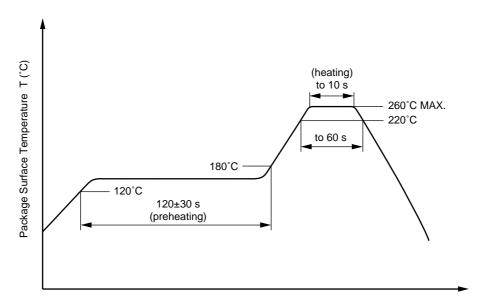
★ RECOMMENDED SOLDERING CONDITIONS

- (1) Infrared reflow soldering
 - Peak reflow temperature
 - Time of peak reflow temperature
 - Time of temperature higher than 220°C
 - Time to preheat temperature from 120 to 180°C
 - Number of reflows
 - Flux

260°C or below (package surface temperature) 10 seconds or less 60 seconds or less 120±30 s Three Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



Time (s)

(2) Wave soldering

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times
 One
- Flux

Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(3) Cautions

• Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.



Subject: Compliance with EU Directives

CEL certifies, to its knowledge, that semiconductor and laser products detailed below are compliant with the requirements of European Union (EU) Directive 2002/95/EC Restriction on Use of Hazardous Substances in electrical and electronic equipment (RoHS) and the requirements of EU Directive 2003/11/EC Restriction on Penta and Octa BDE.

CEL Pb-free products have the same base part number with a suffix added. The suffix –A indicates that the device is Pb-free. The –AZ suffix is used to designate devices containing Pb which are exempted from the requirement of RoHS directive (*). In all cases the devices have Pb-free terminals. All devices with these suffixes meet the requirements of the RoHS directive.

This status is based on CEL's understanding of the EU Directives and knowledge of the materials that go into its products as of the date of disclosure of this information.

Restricted Substance per RoHS	Concentration Limit per RoHS (values are not yet fixed)	Concentration contained in CEL devices		
Lead (Pb)	< 1000 PPM	-A Not Detected	-AZ (*)	
Mercury	< 1000 PPM	Not Detected		
Cadmium	< 100 PPM	Not Detected		
Hexavalent Chromium	< 1000 PPM	Not Detected		
РВВ	< 1000 PPM	Not Detected		
PBDE	< 1000 PPM	Not Detected		

If you should have any additional questions regarding our devices and compliance to environmental standards, please do not hesitate to contact your local representative.

In no event shall CEL's liability arising out of such information exceed the total purchase price of the CEL part(s) at issue sold by CEL to customer on an annual basis.

See CEL Terms and Conditions for additional clarification of warranties and liability.

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